MITSUI
KINZOKU

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NEWS RELEASE

VSP™ Electro-Deposited Copper Foil for High-Frequency Circuit Boards Production Capacity Additionally Enhanced

— Additional expansion of both Taiwan and Malaysia plants
increasing capacity by 45%, to 840 tons per month —

Mitsui Mining & Smelting Co., Ltd. (NOU Takeshi, President; hereinafter "Mitsui Kinzoku") announces that it has decided to increase the production capacity of its VSP™ electro-deposited copper foil for high-frequency circuit boards, which is currently manufactured at its Taiwan Plant (Taiwan Copper Foil Co., Ltd.) and Malaysia Plant (Mitsui Copper Foil (Malaysia) Sdn Bhd), by approximately 45%, from the 580 tons announced as of January 7, 2025 to 840 tons per month.

Mitsui Kinzoku's VSP™ copper foil for high-frequency circuit boards has been used in servers, routers, switches and other high-performance communication infrastructure equipment, since it greatly contributes to the reduction of transmission loss in printed circuit boards at high frequency signal bands. Currently, its demand is acceleratingly growing faster than originally planned for AI server-related applications, particularly Mitsui Kinzoku's VSP™ HVLP5 under the transition from the development phase to the mass-production phase, and further expansion is expected to the future.

In these circumstances, in addition to the increase in production capacity from 420 tons per month to 580 tons per month announced on January 7, 2025, it has already completed the expansion to 620 tons per month improving productivity with its existing facilities in Taiwan Plant. Additionally, it will plan to progressively increase production capacities in both Taiwan and Malaysia plants by repurposing existing facilities to achieve production capacity of 720 tons by March 2026, and 840 tons per month by September 2026.

Through these measures Mitsui Kinzoku's VSP™ production capacity will increase, however it will continue to consider further expansion in response to growing demand in the future to fully meet strong demand.

Mitsui Kinzoku will contribute to the realization of a sustainable society by implementing our its vision for 2030, "Building new businesses -and the future- with our material intelligence," based on its purpose, "We promote the well-being of the world through a spirit of exploration and diverse technologies."

■ VSP™ production capacity transition (for reference)

(Unit: tons per month)	Before enhancements	Current	Mar. 2026	Sep. 2026
Taiwan	420	560	600	720
Malaysia	0	60	120	120
Total	420	620	720	840

[Contact]
Corporate Communications Department, Corporate Planning & Control Sector,
Mitsui Mining & Smelting Co., Ltd.
TEL: 03-5437-8028　E-mail: PR@mitsui-kinzoku.com

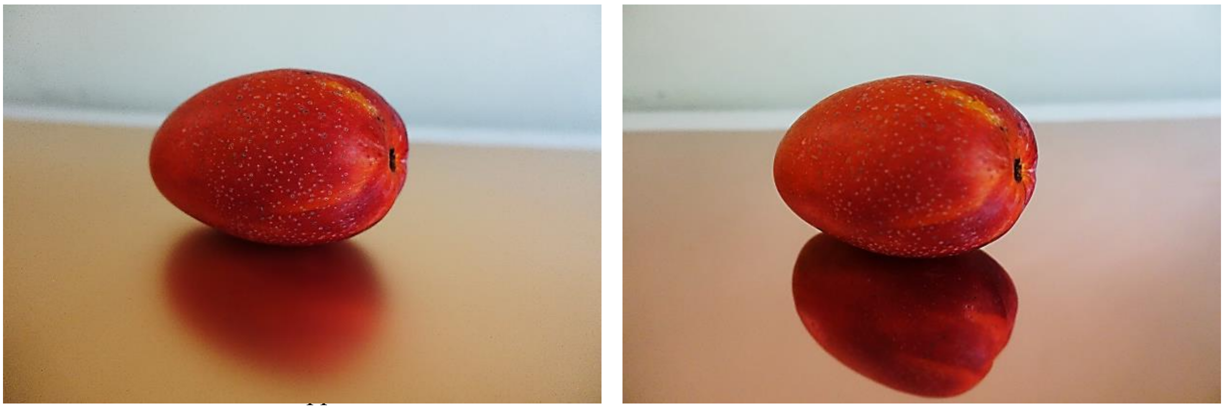

Photo: A reflection of an apple mango in a copper foil surface

* VSP™ is characterized by its outstanding surface smoothness comparable to that of a mirror.

(Reference)

Main functions of VSP™:

It is a copper foil for high-frequency circuit boards for communication infrastructure devices, including servers, switches, routers and base stations.